



# 4/1-25-02  
Dade

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**In re Application of:**

Kinsman et al.

**Serial No.:** 09/917,127

**Filed:** June 27, 2001

**For:** METHOD FOR FABRICATING A CHIP  
SCALE PACKAGE USING WAFER LEVEL  
PROCESSING AND DEVICES RESULTING  
THEREFROM

**Examiner:** Unknown

**Group Art Unit:** 2815

**Attorney Docket No.:** 3572.1US (97-1243.1)

CERTIFICATE OF MAILING

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1.8(a)(1)(ii)

Joseph A. Walkowski  
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PRELIMINARY AMENDMENT

Box Non-Fee Amendment  
Commissioner for Patents  
Washington, D.C. 20231

Sir:

Prior to examination of the above-referenced patent application on the merits, entry of the amendments as set forth herein is respectfully solicited.

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